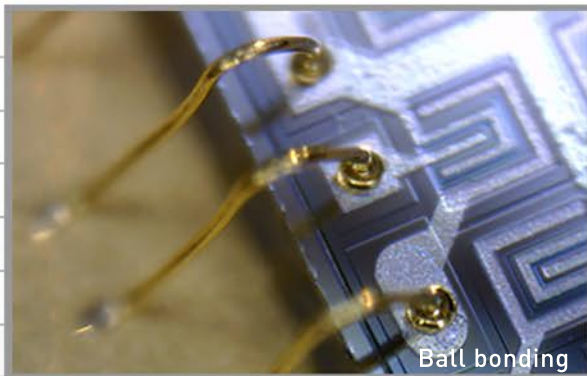


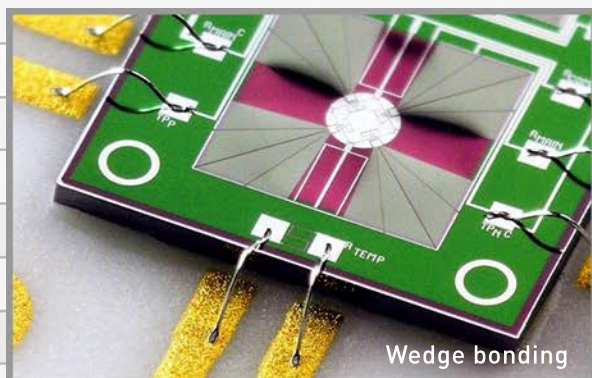


HB05 Wedge & Ball Bonder

Manual Wire Bonder



- + Wedge, Ball, Bump and Ribbon bonding
- + 17 μ to 75 μ Wire and 25 μ x 250 μ Ribbon
- + 4,3" TFT Display & Multi Button
- + Deep-Access Wedge 16mm / Ball 13mm
- + Bond Arm Length 165mm
- + Motorized Tail Control
- + 20 Program Storage Capacities
- + Electronic Ball Size Control



- + Pick & Place Option
- + Pull Tester Option

HB05 Thermosonic Wire Bonder for Wedge & Ball Bonding

The HB05 is a **Bench Top Size Wire Bonder**, ideal for laboratories and pilot production lines.
One Bond Head for bonding in Ball/Wedge or Wedge/Wedge bonding mode. Only tool change necessary.
 Easy operation with **TFT Display**, direct access and simple adjustment of all bond parameters.

Technical Specifications

Bonding Methode	Wedge-Wedge, Ball-Wedge, Ribbon- & Bumb- bonding
Gold wire diameter	17 - 75 μm (0,7 - 3 mil)
Aluminium wire diameter	17 - 75 μm (0,7 - 3 mil)
Ribbon size	max. 25 x 250 μm (1 x 10 mil)
Ultrasonic system	63,3 kHz Transducer PLL Control
Ultrasonic power	0 - 10 Watt Output
Bond time	0 - 20000 msec.
Bond force	5 - 200 cN (350 cN option)
Bonding tool	1,58 \varnothing 19 mm length (0,0624" x 0,750")
Manual Wire Spool	50,8 mm (2")
Wire termination	Bond Head Tear
Wire feed angle	90°
Clamp movement	Motorized, Up / Down
Ball size control	Electronic
Throat depth	165 mm (6,5")
Fine Table motion	15 mm (0,59")
Mouse ratio	6:1
Temperature controller	up to 250°C +/- 1°C
Electrical Requirements	100 - 240V +/-10% 50/60 Hz 10A max.
Physical Dimensions	550 (22") x 450 (18") x 250 mm (10")
Weight	Net 25 kg
Industry Standards	CE standards

Accessories:



H26 60mm \varnothing
Heater Stage



H29 90mm \varnothing
Heater Stage



H21 Heater Stage
100 x 100mm



H69 Bond Starter Kit

Specifications are subject to change without prior notice



TPT Wire Bonder GmbH & Co.KG
 Einsteinstr. 10 D-85757 Karlsfeld
 Tel.: +49 (0) 8131 / 58604
 www.tpt.de / info@tpt.de

Made in Germany